

HVC355B

Variable Capacitance Diode for VCO

REJ03G0084-0100Z

(Previous: ADE-208-416)

Rev.1.00

Sep.17.2003

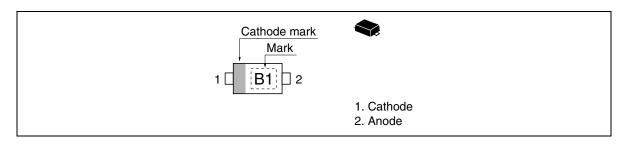
Features

- High capacitance ratio. (n = 2.20 min)
- Low series resistance. (rs = $0.6 \Omega \text{ max}$)
- Ultra small Flat Package (UFP) is suitable for surface mount design.

Ordering Information

| Type No. | Laser Mark | Package Code |
|----------|------------|--------------|
| HVC355B | B1 | UFP |

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

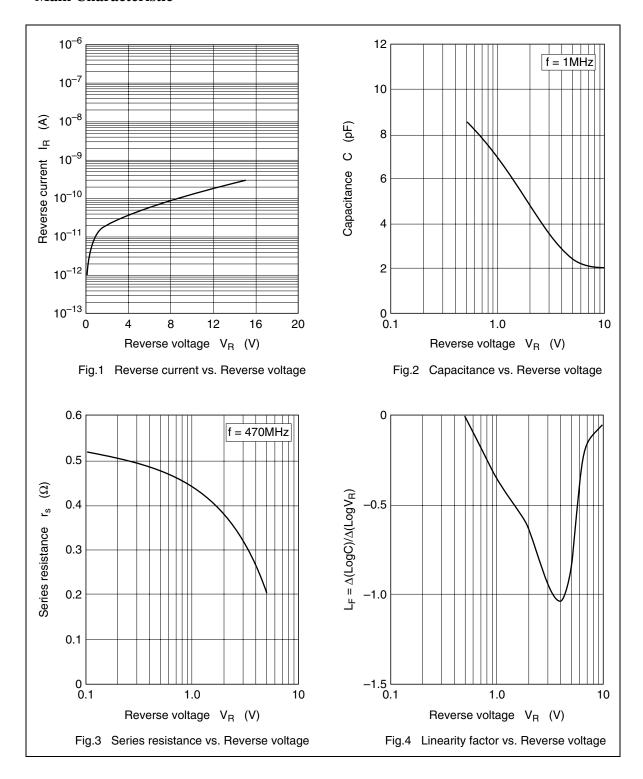
| Item | Symbol | Value | Unit |
|----------------------|--------|-------------|------|
| Reverse voltage | V_R | 15 | V |
| Junction temperature | Tj | 125 | °C |
| Storage temperature | Tstg | -55 to +125 | °C |

Electrical Characteristics

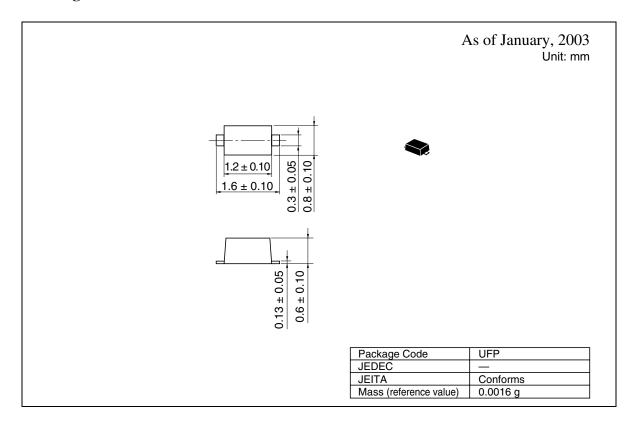
 $(Ta = 25^{\circ}C)$

| Item | Symbol | Min | Тур | Max | Unit | Test Condition |
|-------------------|-----------------|------|-----|------|------|-----------------------------------|
| Reverse current | I _{R1} | _ | _ | 10 | nA | V _R = 15 V |
| | I _{R2} | _ | _ | 100 | _ | V _R = 15 V, Ta = 60°C |
| Capacitance | C ₁ | 6.40 | _ | 7.20 | pF | V _R = 1 V, f = 1 MHz |
| | C ₄ | 2.55 | _ | 2.95 | _ | V _R = 4 V, f = 1 MHz |
| Capacitance ratio | n | 2.20 | _ | _ | _ | C ₁ /C ₄ |
| Series resistance | r _s | _ | _ | 0.6 | Ω | V _R = 1 V, f = 470 MHz |

Main Characteristic



Package Dimensions



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